

## Contacts for new product

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## Combination Bonder and Pull/Shear Tester Series 56xx

F&K Delvotec Semiconductor GmbH, Braunau, Austria, closes the technological gap between manual and automatic wire bonders. In addition to that the functions of a pull/shear tester are integrated into this system.

### Technical Information Heavy Wire Version

- wire size 100 to 500  $\mu\text{m}$
- 360° rotary bond head
- technical sequences and ultrasonic generators identical to the F&K Delvotec's automatic machines
- with only one machine base a wire bonder is converted to a pull/shear tester within minutes – without tools or adjustments
- PC control in Windows 2000 standard for program selection is state of the art and above
- available bond methods are Ball/Wedge, Au/Al Wedge/Wedge, Al heavy wire and ribbon
- all common wires/ribbon can be processed
- pull test ranges from 100 cN to 30 N
- shear test of ranges from 500 cN to 50 N
- tweezer or peel test units are available



### Target Groups and Applications

Application areas are primarily the repair of highly complex, expensive circuits, manufacturing of prototypes, small series and laboratory applications. Shortest change over time (< 3 min.) combined with the bond test capability help to reduce costs while offering increased productivity.

The decision between a manual and an automatic machine is often crucial for the investment. The 56xx series is the most economic choice compared to a fully automatic machine and the most flexible compared to a manual/semiautomatic bonder with an additional the pull/shear tester. All bond or test units can be retrofitted. F&K Delvotec covers the complete product range from manual to fully automatic wire and die bonders.